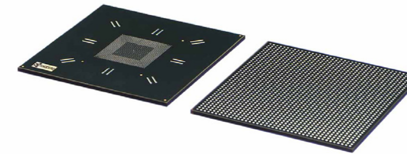
THE NEW VALUE FRONTIER

The Future is Created with High Density Wiring Boards and IC Packages.

KYOCERA SLC Technologies (KST) provides products such as IC Packages and high density wiring boards into the market.
These products are coming with high performance characteristics, excellent reliability and good cost performance simultaneously.
KST support a total solution focusing on customers' needs for higher density assembly.

High-Speed Transmission and Fine Pattern Technology enables High Performance of Electronics Device

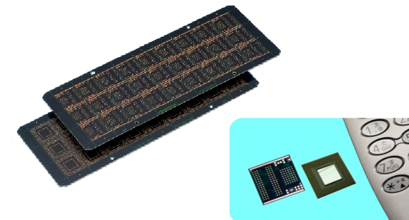
High Density Organic Flip Chip Substrates



FCBGA Substrate for High-end ASICs

KYOCERA SLC Technologies' Flip Chip Substrate offers the solutions to the market that requires high I/O count of LSI and Over GHz high Speed device by adopting the industry's highest and the finest density design to those applications such as ASICs, DSPs, Network Processors, Graphic Processors, Optical interface cards and digital electric appliance such as mobile phones and digital cameras.

System in Package Substrates

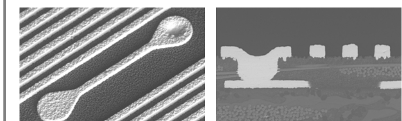


SiP Substrate for 3D Chip stack assemble

- Fine pitch line and space is available with 15um Line width and 15um space at build up layers.
- Area array flip chip pad and 40um pitch peripheral flip chip pad is available.
- Thin build up laminate for SiP applications.
- Both flip chip and wire bonding pattern can live together on the same board.
- Environmental friendly material set is available. (Halogen free, Lead free)

System in Package (SiP) is inevitable for electronic components such as mobile phones, digital cameras and various others hand-held applications.
KYOCERA SLC Technologies can work together with customers to design a SiP substrate to meet all the product requirements.

ADVANCED FINE PATTERN TECHNOLOGY



20 micron Wiring Pattern on Prepreg Sheet

KYOCERA SLC Technologies Corporation

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